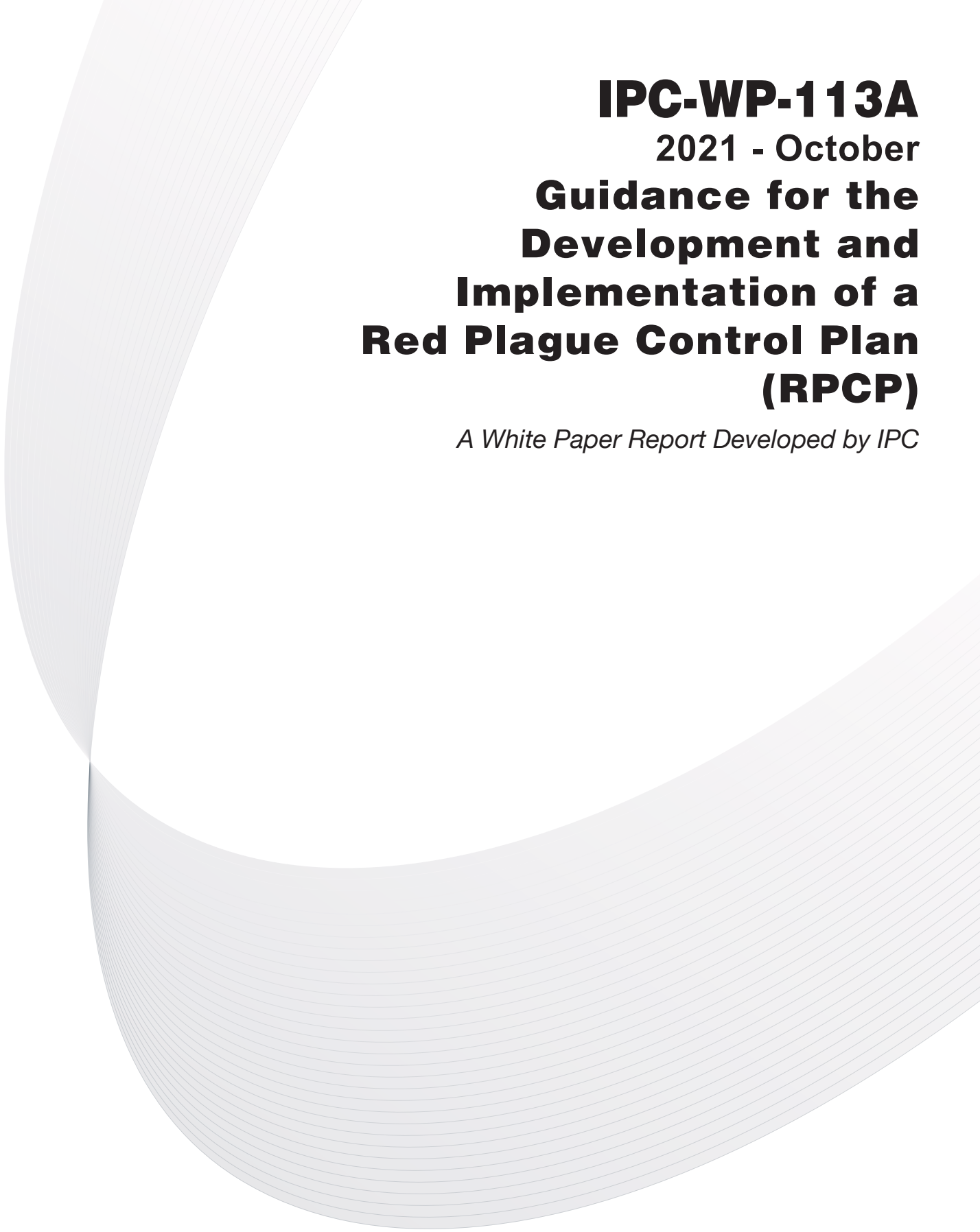




IPC-WP-113A

2021 - October

Guidance for the Development and Implementation of a Red Plague Control Plan (RPCP)

A White Paper Report Developed by IPC



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Guidance for the Development and Implementation of a Red Plague Control Plan (RPCP)

Developed by the Wire Harness Design Task Group (7-31k)
of the Product Assurance Committee (7-30) of IPC

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Users of this publication are encouraged to participate in the
development of future revisions.

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